

Listing Of Claims

Claims 1-56 (Canceled)

57. (new) A semiconductor package comprising:
a leadframe;
a die on the leadframe; and
a plastic body comprising a first polymer member on the die or the leadframe, and a second polymer member encapsulating the first polymer member, the first polymer member and the second polymer member configured to adjust a selected characteristic of the package.

58. (new) The semiconductor package of claim 57 wherein the selected characteristic comprises a package bow.

60. (new) The semiconductor package of claim 57 wherein the selected characteristic comprises a package warpage.

61. (new) The semiconductor package of claim 57 wherein the first polymer member comprises a molded material.

62. (new) The semiconductor package of claim 57 wherein the first polymer member comprises a tape material.

63. (new) The semiconductor package of claim 57 wherein the first polymer member encapsulates the die.

64. (new) The semiconductor package of claim 57 wherein the first polymer member and the second polymer member are selected to provide a substantially equal volume of a molding compound on either side of the leadframe.

65. (new) A semiconductor package comprising:
a leadframe;
a die on the leadframe;
a first polymer member on the die or the leadframe; and
a second polymer member encapsulating the first polymer member;
the first polymer member and the second polymer member having selected geometries configured to provide a selected characteristic for the package.

66. (new) The semiconductor package of claim 65 wherein the selected geometries comprise volumes of a molding compound.

67. (new) The semiconductor package of claim 65 wherein the selected geometries are configured to reduce a package bow.

68. (new) The semiconductor package of claim 65 wherein the selected geometries are configured to reduce a package warpage.

69. (new) The semiconductor package of claim 65 wherein the first polymer member comprises a molding compound substantially encapsulating the die.

70. (new) The semiconductor package of claim 65 wherein the first polymer member and the second polymer member comprise a molded plastic.

71. (new) A semiconductor package having a parting line comprising:

a leadframe;

a die on the leadframe;

a polymer member on the die or the leadframe; and

a plastic body comprising a molding compound encapsulating the polymer member and at least a portion of the leadframe;

the polymer member configured to provide a substantially equal volume of the molding compound on either side of the parting line.

72. (new) The semiconductor package of claim 71 wherein the polymer member comprises a material selected from the group consisting of epoxy, silicone, room temperature vulcanizing (RTV) and polyimide.

73. (new) The semiconductor package of claim 71 wherein the polymer member comprises a tape material.

74. (new) The semiconductor package of claim 71 wherein the polymer member encapsulates the die.

75. (new) The semiconductor package of claim 71 wherein the leadframe has a lead-on-chip configuration.

76. (new) The semiconductor package of claim 71 wherein the die is attached and wire bonded to the leadframe.

77. (new) The semiconductor package of claim 71 wherein the polymer member comprises the molding compound.

78. (new) A semiconductor package comprising:
a leadframe;
a die on the leadframe; and
a first polymer member on the die or the leadframe; and
a second polymer member on the first polymer member and the leadframe;

the first polymer member configured to provide a selected characteristic in the second polymer member.

79. (new) The semiconductor package of claim 78 wherein the selected characteristic comprises increased rigidity.

80. (new) The semiconductor package of claim 78 wherein the second polymer member comprises substantially equal volumes of a molding compound on either side of the leadframe.

81. (new) The semiconductor package of claim 78 wherein the first polymer member substantially encapsulates the die.

82. (new) The semiconductor package of claim 78 wherein the second polymer member substantially encapsulates the first polymer member.